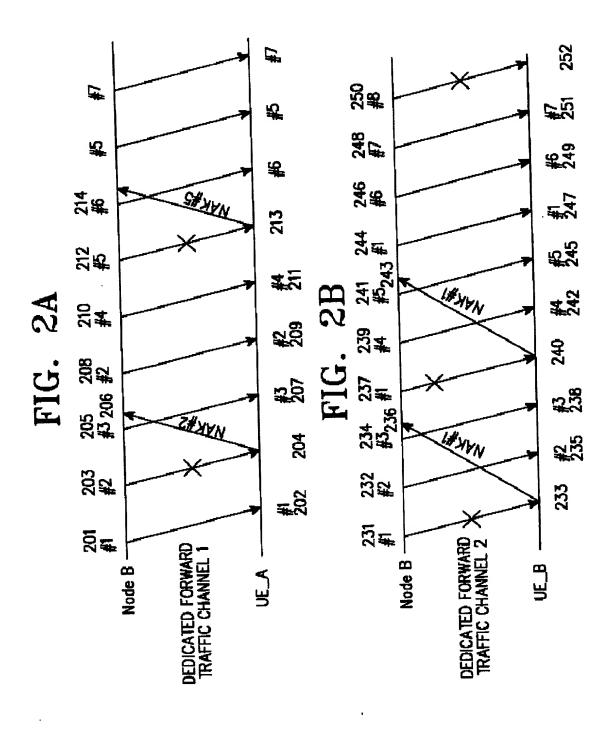


FIG. 1



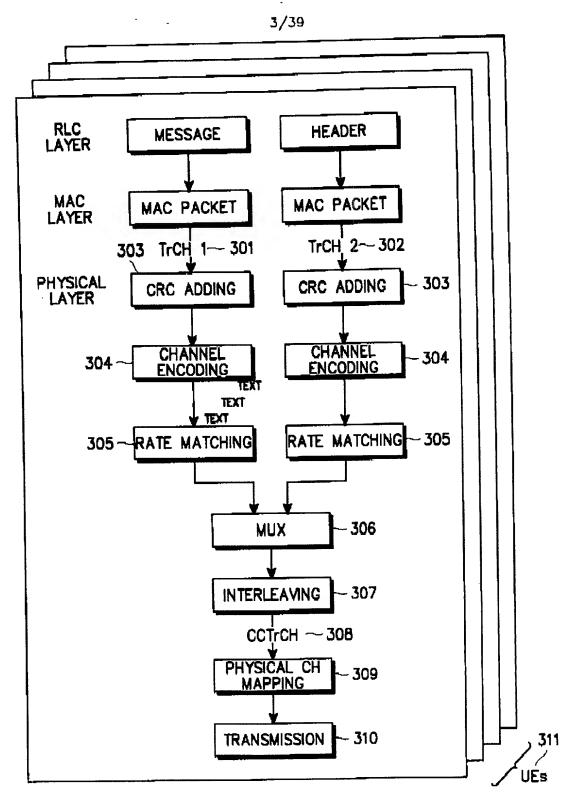


FIG. 3

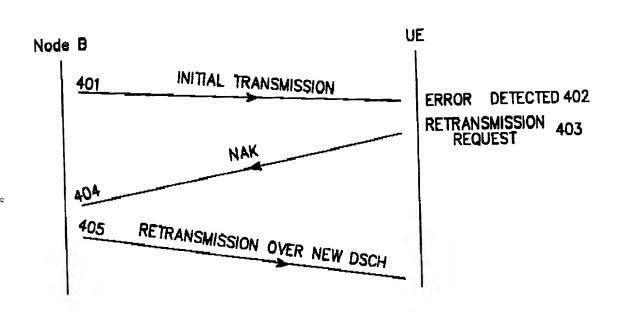
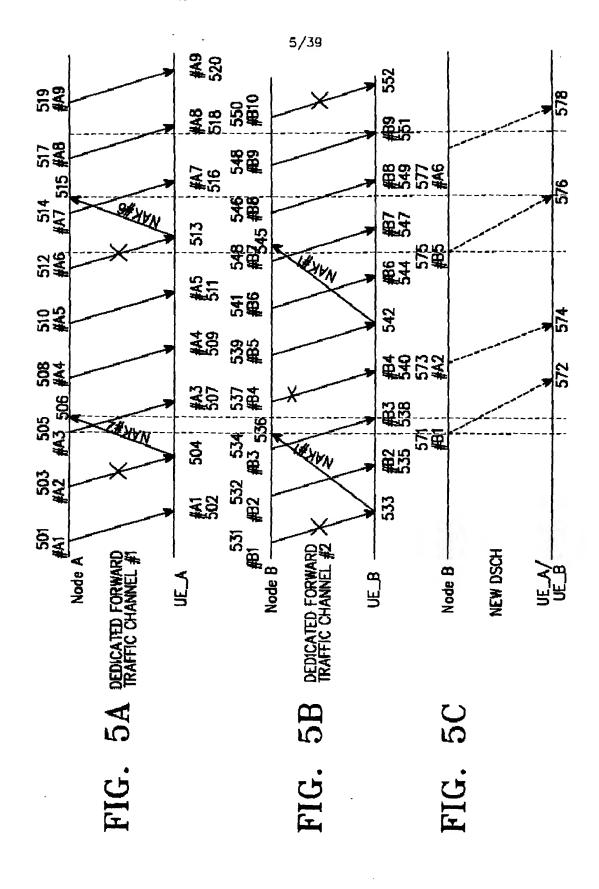


FIG. 4



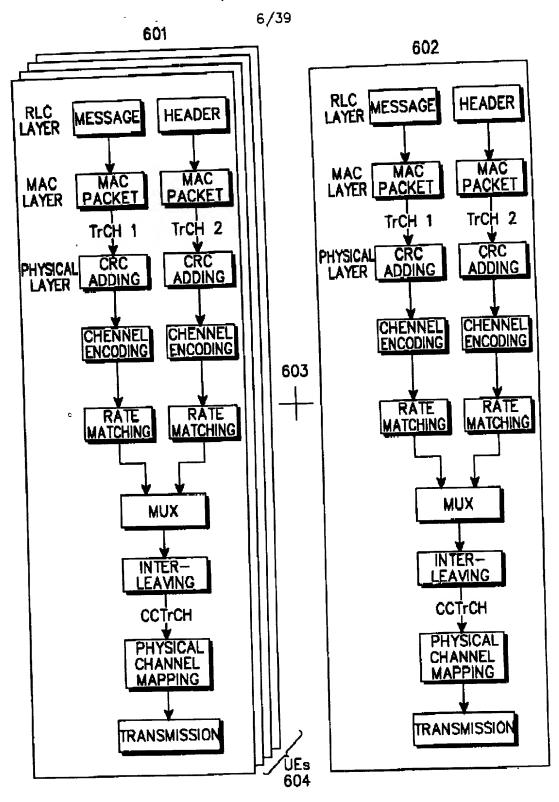


FIG. 6

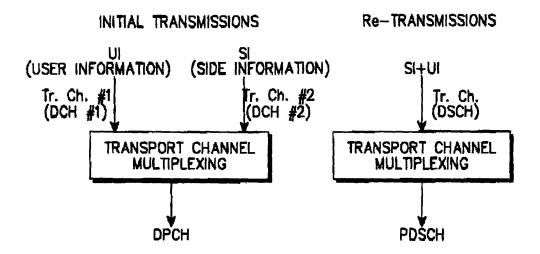


FIG. 7

ļ.d.

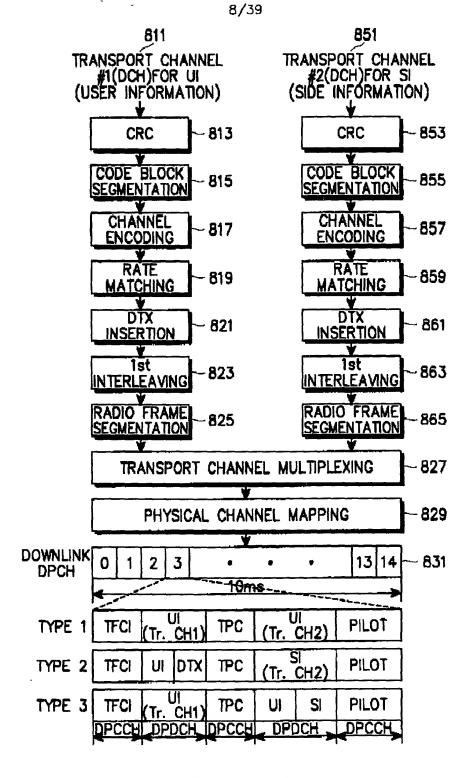


FIG. 8

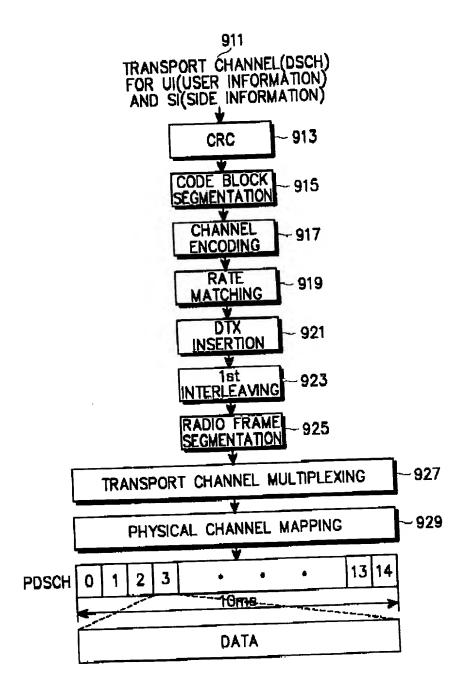


FIG. 9

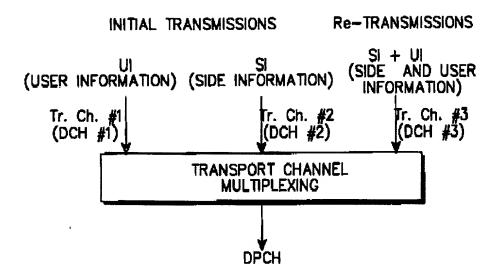


FIG. 11

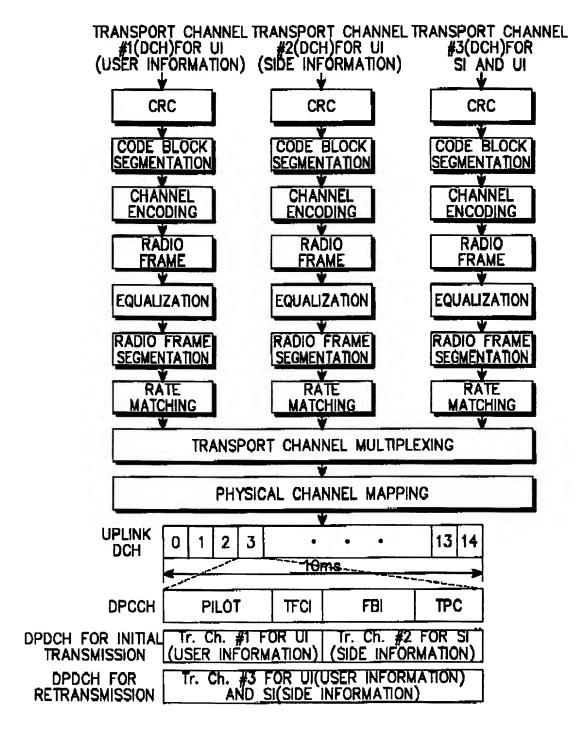
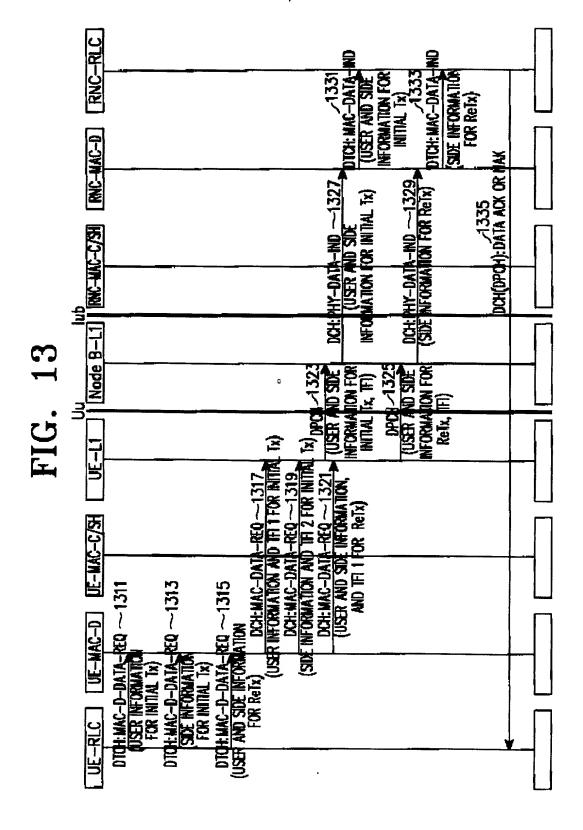
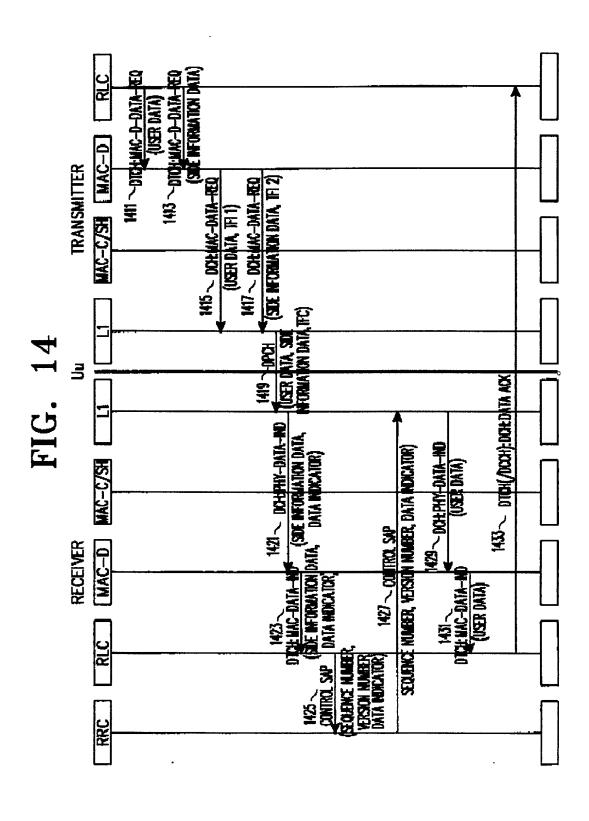


FIG. 12

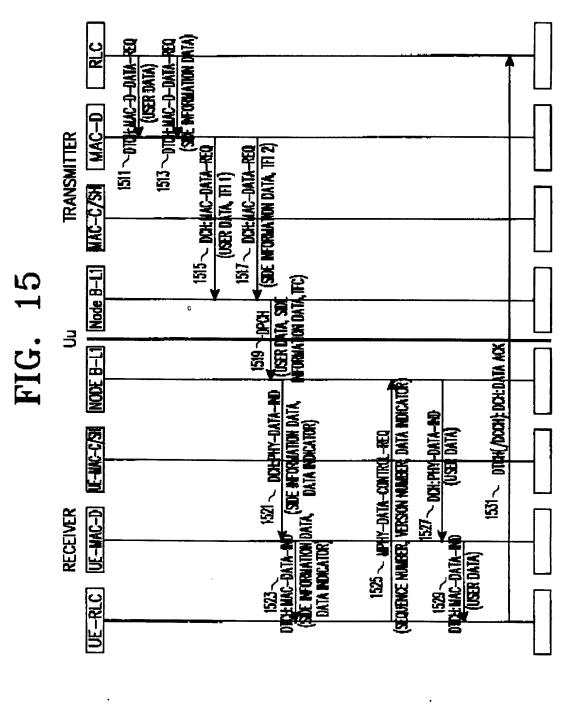




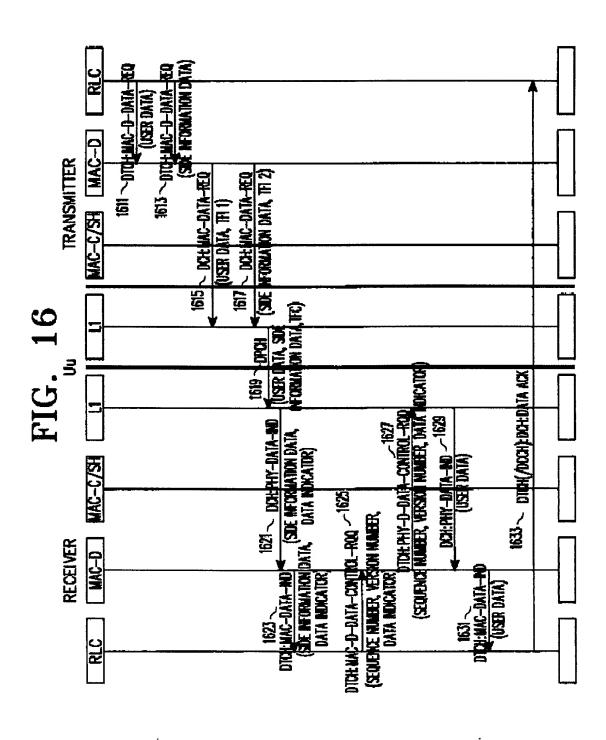












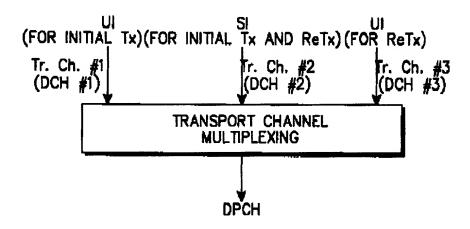


FIG. 17

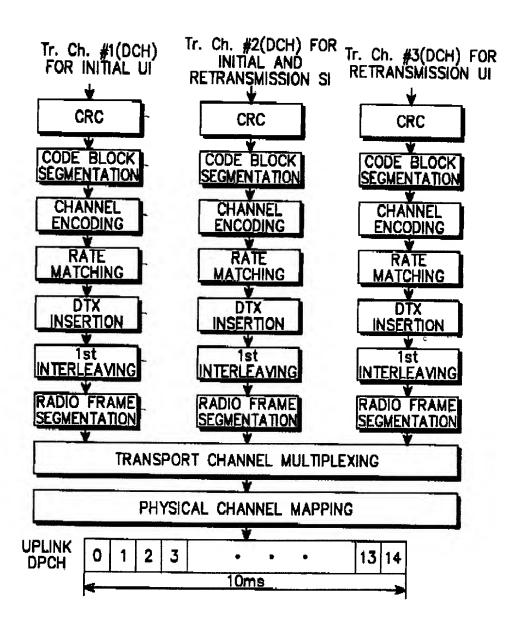
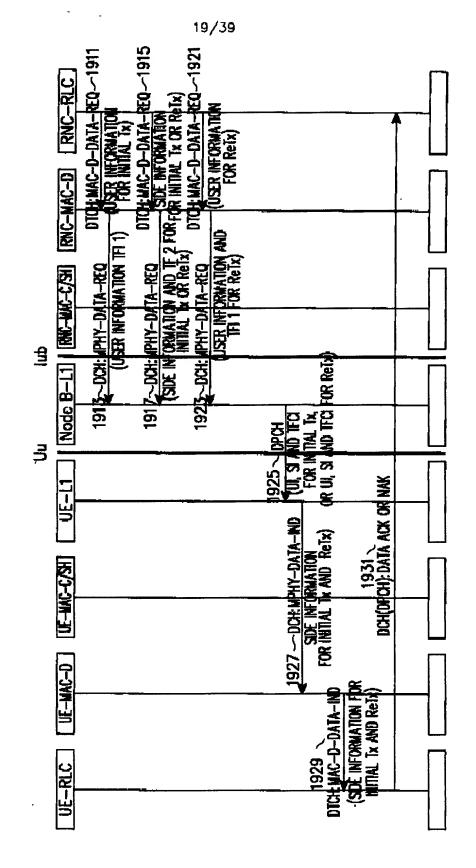


FIG. 18

FIG. 19



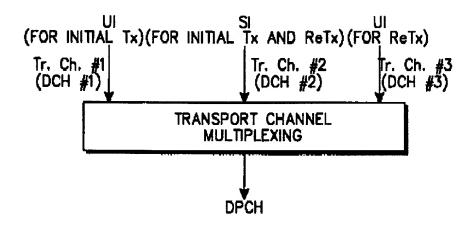


FIG. 20

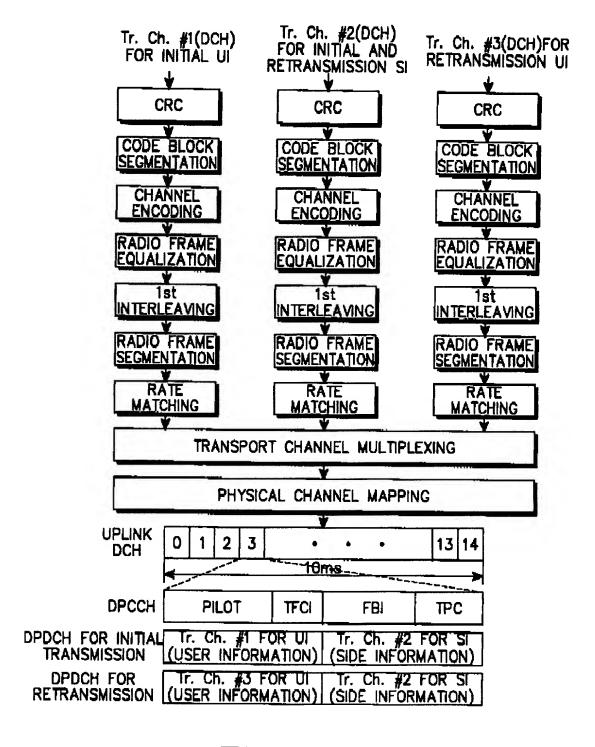
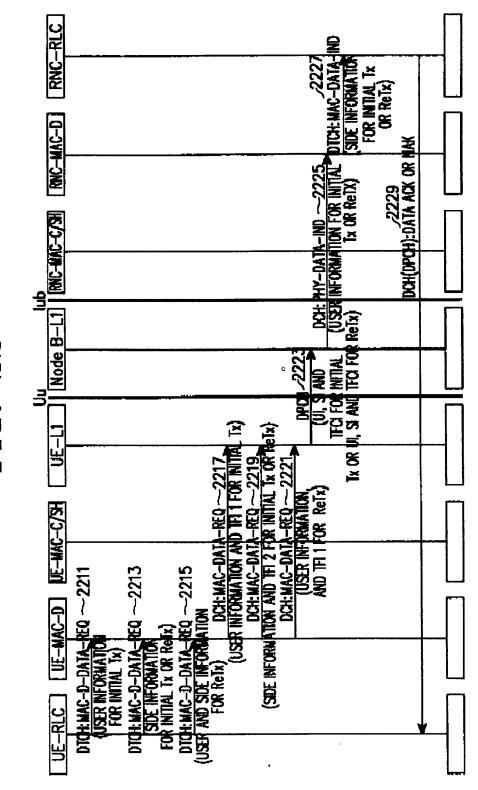


FIG. 21

FIG. 22



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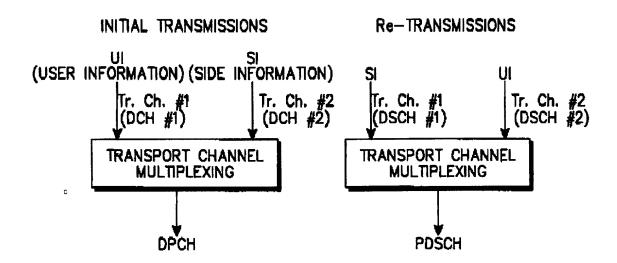


FIG. 23

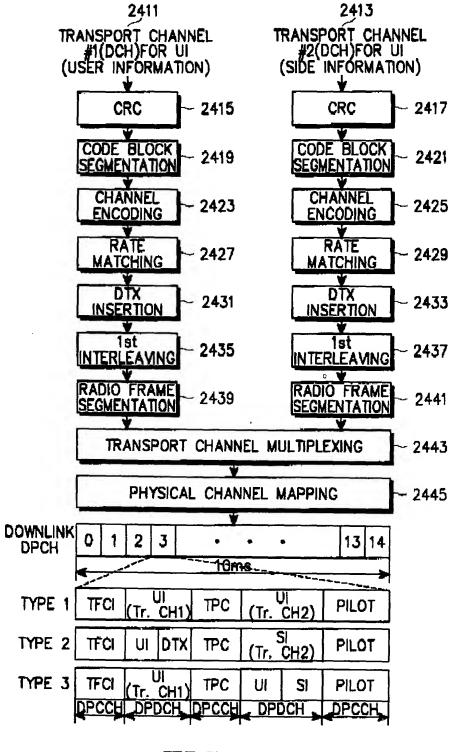


FIG. 24

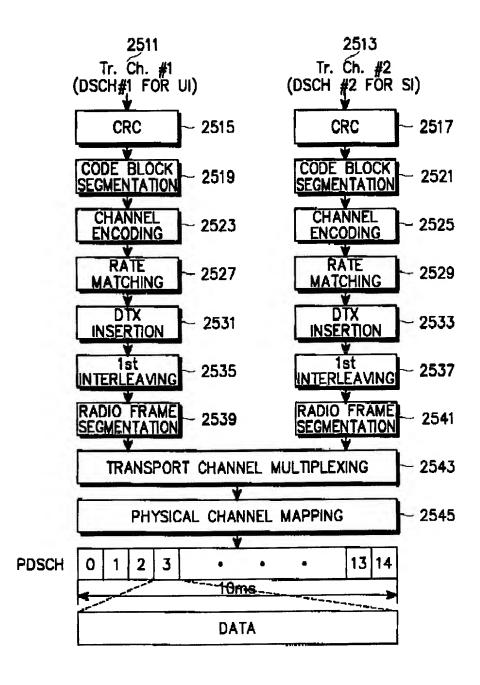
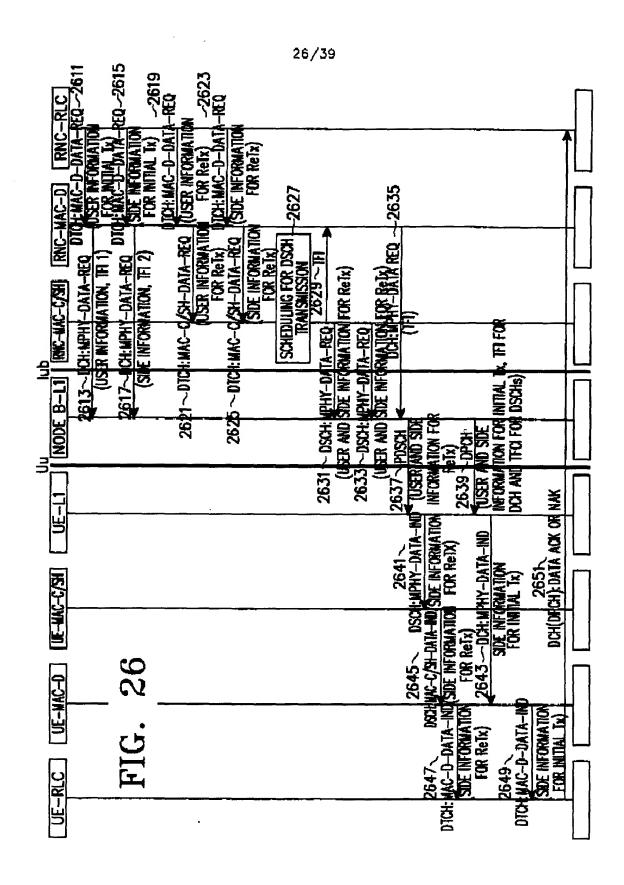


FIG. 25



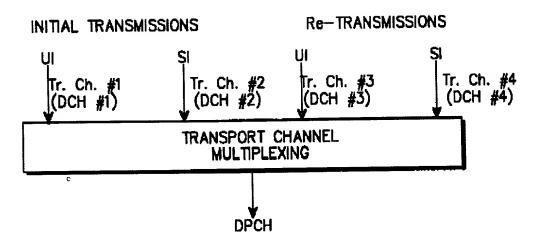


FIG. 27

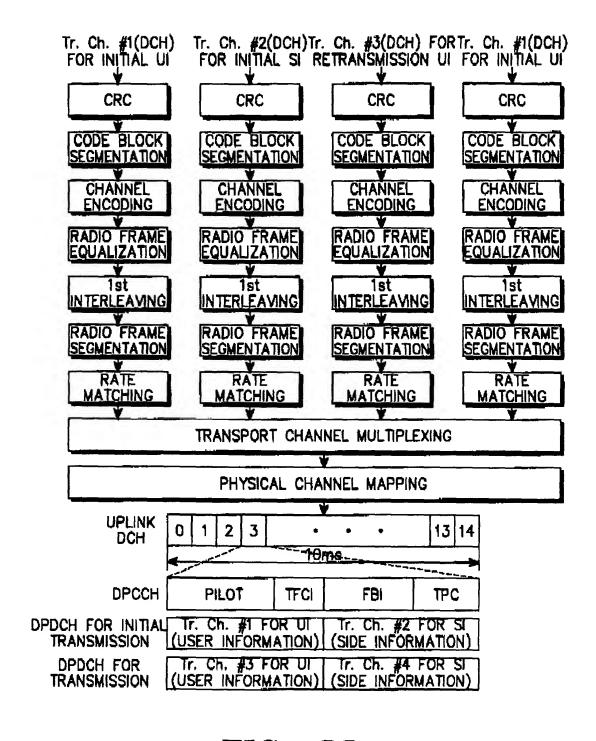
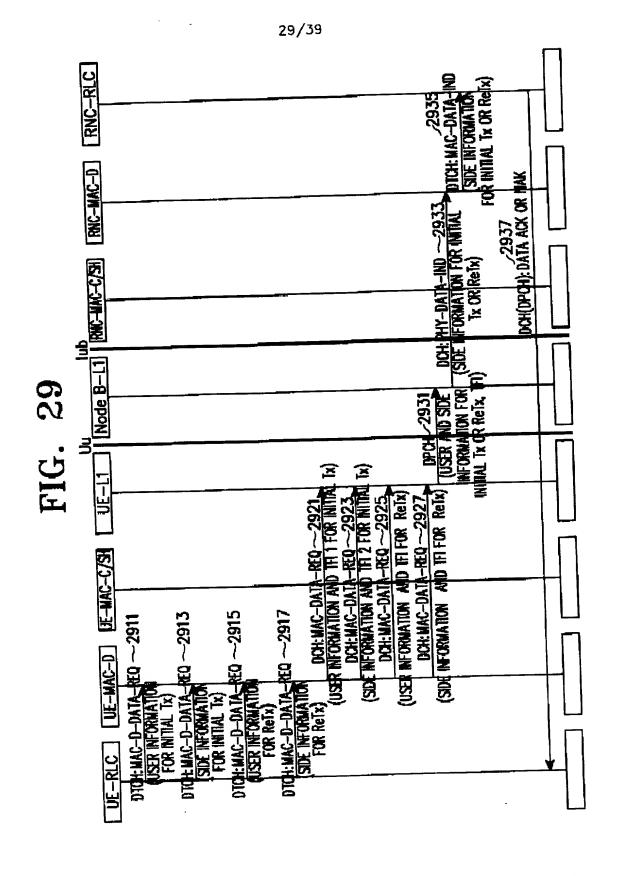


FIG. 28



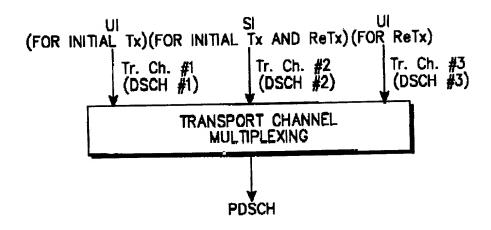


FIG. 30

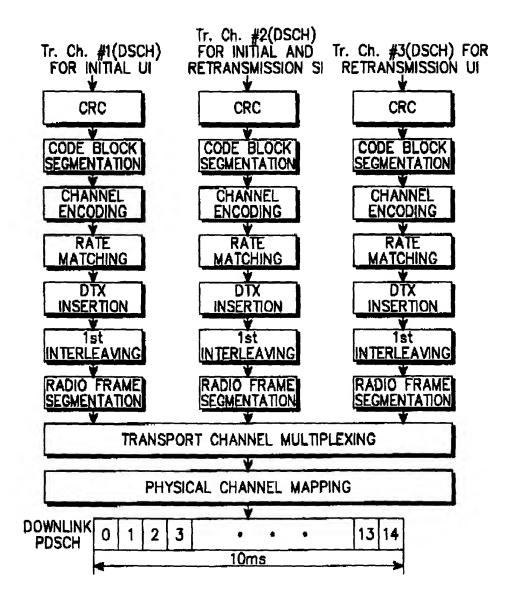
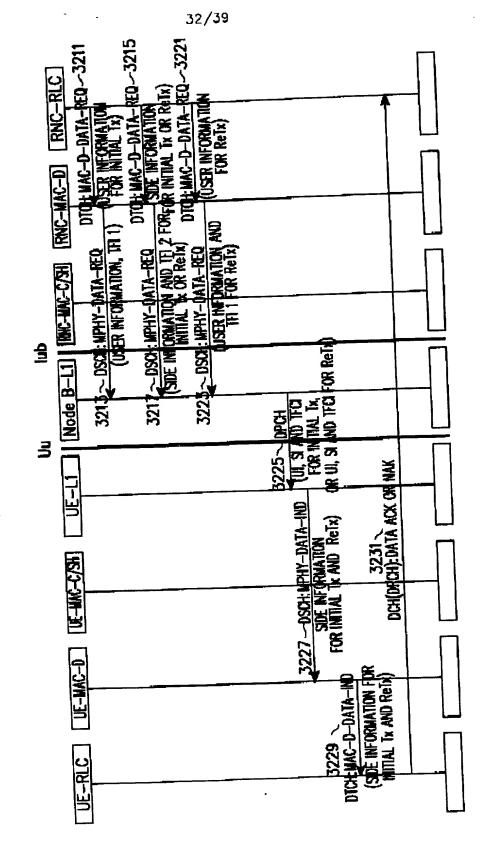


FIG. 31

FIG. 32



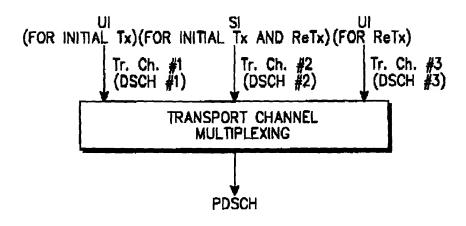


FIG. 33

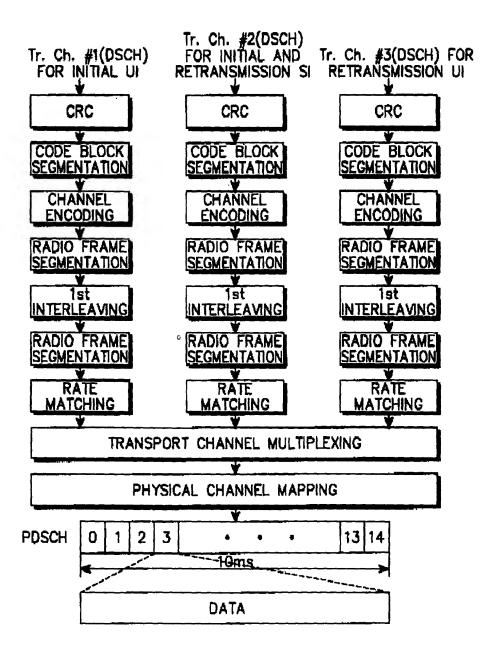


FIG. 34

RNC-RLC RNC-NAC-D .3529 DATA ACK OR HAK Node B-L1 NINTHAL TO OR UI. S AND TECHFOR RETE FIG. 35 LE-MAC-C/SH REMATION AND T 

35/39

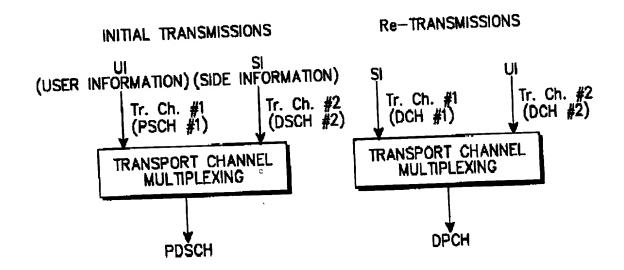
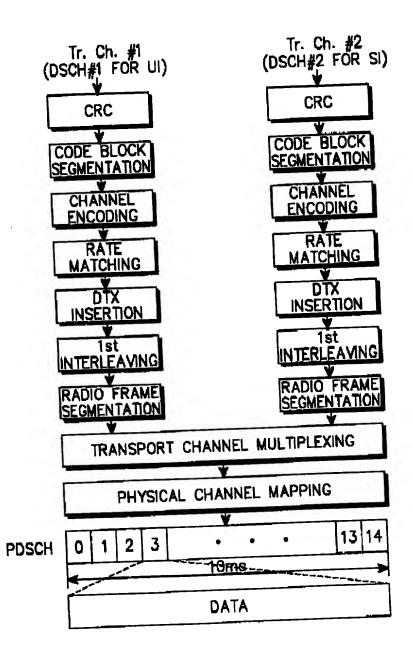


FIG. 36



C

FIG. 37

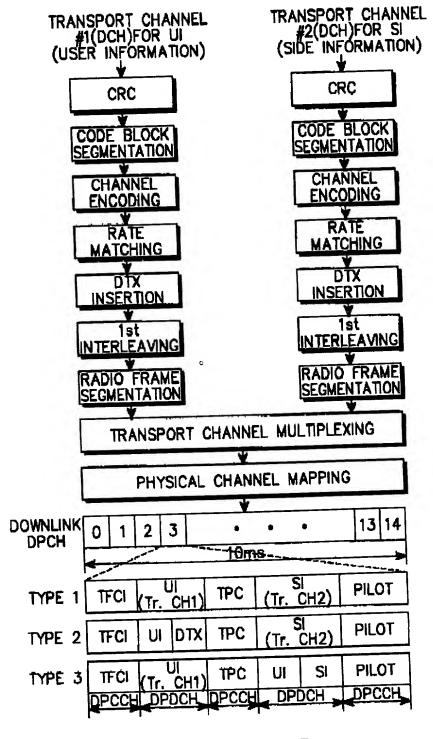


FIG. 38

